

VQFN - 1 mm max height

The drawing illustrates the mechanical specifications of a 28-pin QFN package. The top view shows a square body with a central square pad (29x29) and four groups of pins (14 pins per side). Key dimensions include a total width of 5.1 (4.9) and a total height of 6.1 (5.9). A shaded area in the top-left corner is designated as the 'PIN 1 INDEX AREA'. The side view shows the package's profile with a maximum height of 1.0 (0.8) and a seating plane. The detail view of the pins shows a pitch of 0.5 and a pin height of 0.85. The package is marked with 'PKG' and '28'. A table of tolerances is provided at the bottom right.

0.1	M	C	A	B
0.05	M	C		

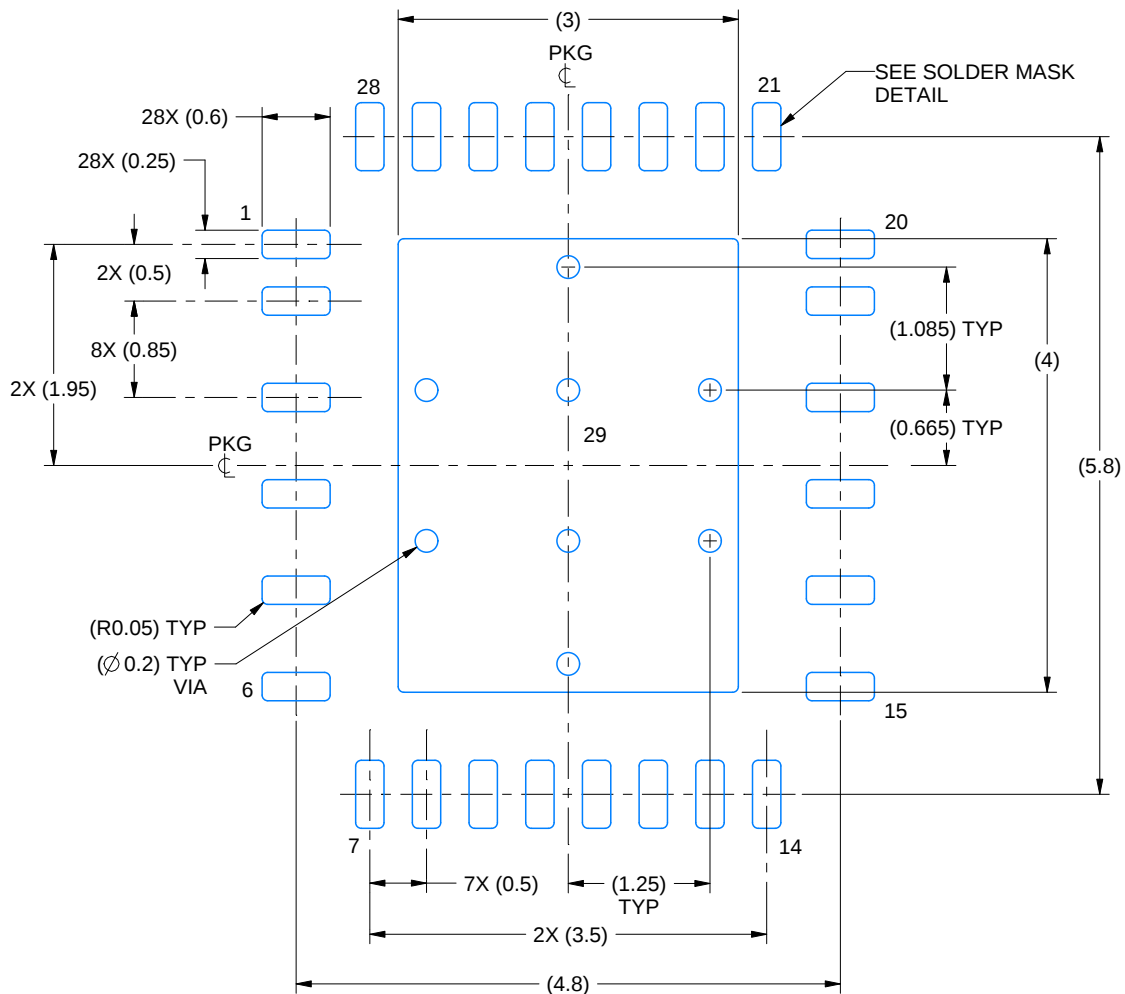
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1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.

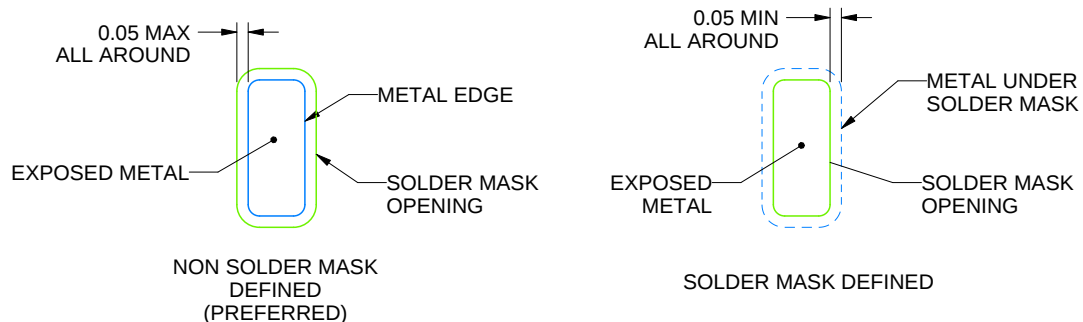
NLG0028B

VQFN - 1 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 15X



SOLDER MASK DETAILS

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NOTES: (continued)

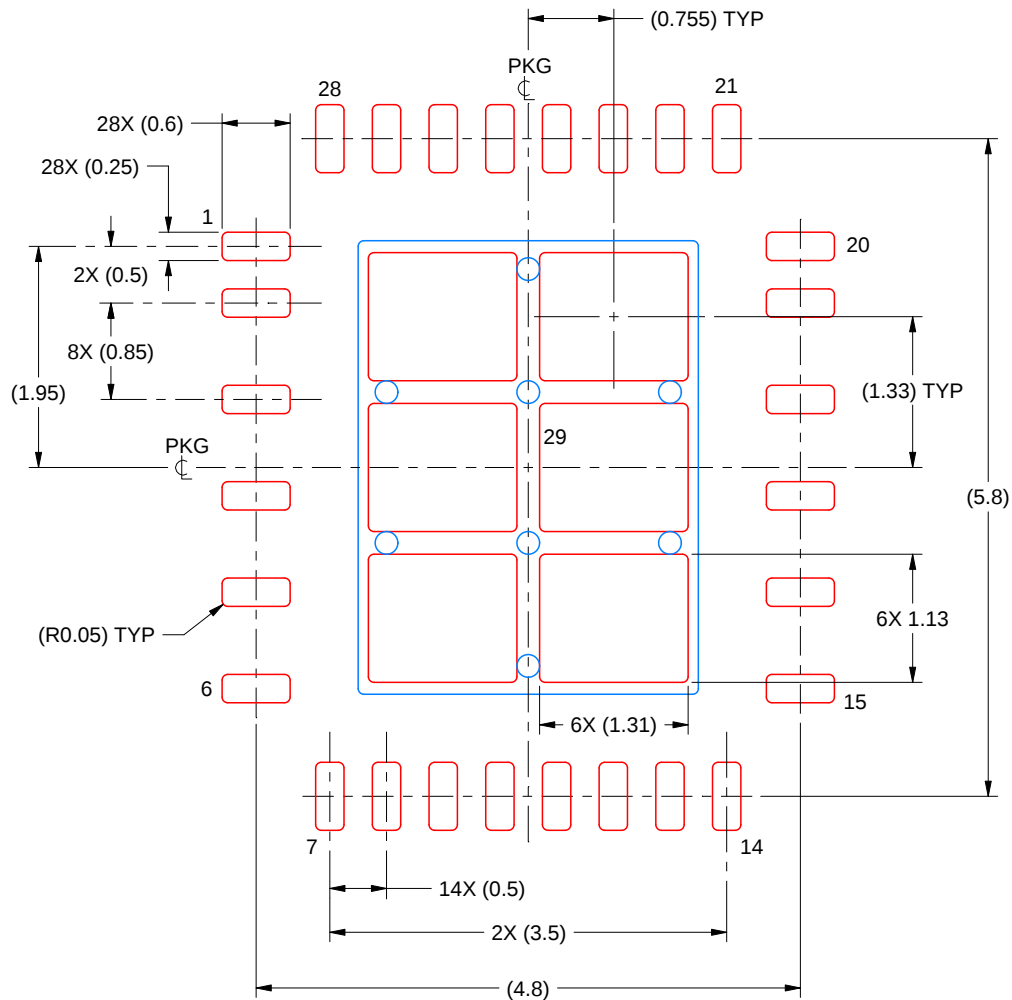
4. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slua271).
5. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.

EXAMPLE STENCIL DESIGN

NLG0028B

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PLASTIC QUAD FLATPACK - NO LEAD



SOLDER PASTE EXAMPLE
BASED ON 0.125 MM THICK STENCIL
SCALE: 15X

EXPOSED PAD 29
74% PRINTED SOLDER COVERAGE BY AREA UNDER PACKAGE

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NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

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